EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	127	sacrificial adj layer and thermally adj grow$3 adj silicon adj dioxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/15 17:27
L2	31	sacrificial adj layer and thermally adj grow$3 adj silicon adj dioxide and remov$3 near4 silicon adj dioxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/15 17:27
L3	27	sacrificial adj layer and thermal near4 silicon adj dioxide and remov$3 near4 silicon adj dioxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/15 17:27
L4	11	sacrificial adj layer and eklund.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/15 17:48
L5	1	09/857803.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/15 17:49
L6	25	("20020127820" | "20040063298" | "5494849" | "5668045" | "5834812" | "5863832" | "5937312" | "5989981" | "6074479" | "6103599" | "6140210" | "6191007" | "6224668" | "6238990" | "6245645" | "6251754" | "6261362" | "6284628" | "6284629" | "6312797" | "6313014" | "6350703" | "6387829" | "6403502" | "6613678").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/15 17:52
L7	0	(substrate or wafer) adj clean$3 and dry$3 near low adj vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/15 17:53
S1	3	(("6323109") or ("6306730") or ("5374564")).PN.	USPAT	OR	OFF	2006/06/15 17:25

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S2	835	(hydrogen or "h.sub.2") adj (implantation or ion adj implantation ion adj implanting or implanting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:53
S3	1231950	vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 08:26
S4	243	S2 and S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 08:28
S5	844	smart adj cut or smartcut	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 08:28
S6	60	S4 and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:44
S7	720	ion adj (cut or cutting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 08:36
S8	85	S7 and S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 08:36
S9	3495856	substrate or die or wafer or chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 08:36

S10	40	S8 and S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 08:42
S11	1	09/505283.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 08:43
S12	3	"20030211705"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 08:43
S13	2996	anodic adj bonding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 09:18
S14	292	S3 and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 09:18
S15	21	S13 and S14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 09:28
S16	412	vacuum adj bonding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 09:28
S17	7	S5 and S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 09:31

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S18	6	low adj vacuum adj bonding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 09:32
S19	13	vacuum adj bonding near4 low	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 09:37
S20	50	vacuum adj bonding same low	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 09:32
S21	4	(dry or drying) near10 low adj vacuum and (bond or bonding) near4 (substrate or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 09:44
S22	1439	(substrate or wafer) adj bonding and (cmp or chemical adj mechanical adj polishing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 09:47
S23	87	bond$4 with low adj vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:34
S24	8	S22 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 09:46
S25	4078	(substrate or wafer) adj bonding and (cmp or chemical adj mechanical adj polishing or polishing or polish or clean)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 09:49

S26	16	S23 and S25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:27
S27	321278	low adj pressure	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:27
S28	180	S27 and (S5 or S7)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:31
S29	756782	(split or splitting or cleave or cleaving or cleaved delaminate or delaminated or delamination)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:13
S30	74	S16 and S29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:34
S31	313	bond$4 with low near4 vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:35
S32	42	S29 and S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:35
S33	649	(split or splitting or cleave or cleaving or cleaved delaminate or delaminated or delamination or splice or splicing or spliced) and (hydrogen or "h.sub.2") adj (implant$6 or ion adj implant$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:15

S34	2655	low adj pressure adj vacuum$3 or low near4 vaccum$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:16
S35	0	S33 and S34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:16
S36	1231950	vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:17
S37	246	S33 and S36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:31
S38	327245	low adj vacuum or low adj pressure	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:32
S39	343872	low adj vacuum or low adj pressure or low near4 vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:36
S40	649	(split or splitting or cleave or cleaving or cleaved delaminate or delaminated or delamination or splice or splicing or spliced) and (hydrogen or "h.sub.2") adj (implant$6 or ion adj implant$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 14:00
S41	111	S40 and S39	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:32

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S42	35229	low adj vacuum or low near4 vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:36
S43	18	S40 and S42	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:40
S44	9	annealing near4 low adj vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:45
S45	4	(smart adj cut or smartcut) and annealing and low adj vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:46
S46	17	(anneal$4) near4 low adj vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:46
S47	5	(smart adj cut or smartcut) and anneal$4 and low adj vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:47
S48	4	(ion adj cut$4) and anneal$4 and low adj vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:52
S49	268	anneal$4 near7 low adj pressure	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 14:17

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S50	0	S40 and S49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:53
S51	835	(hydrogen or "h.sub.2") adj (implantation or ion adj implantation ion adj implanting or implanting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:53
S52	0	S51 and S49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 13:54
S53	3919	simox or separation adj by adj implant$4 adj oxygen	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 14:08
S54	9	S49 and S53	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 14:01
S55	33	ion adj implant$4 and S49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 14:08
S56	174	anneal$4 near7 low near5 vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 14:17
S57	23	S49 and S56	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 14:18

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S58	0	S51 and S57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 14:18
S59	0	S51 and S56	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 14:18